

CORRECT
VERSION
for printing
mw
12/04

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

1. (Previously Amended) A polyamide resin composition consisting essentially of:
100 parts by weight of a polyamide resin mixture comprising
(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof and
(B) 10 to 80% by weight of an aromatic polyamide resin;
and
(C) 0 to 300 parts by weight of an inorganic filler,
said aromatic polyamide resin having diamine units comprising 10 to 50 mol% of paraxylylenediamine units and 50 to 90 mol% of methaxylylenediamine units, and aliphatic dicarboxylic acid units.
2. (Original) The polyamide resin composition according to claim 1, wherein the amount of the inorganic filler (C) blended is 45 to 150 parts by weight based on 100 parts by weight of the polyamide resins (A) and (B).
3. (Original) The polyamide resin composition according to claim 1, wherein the amount of the inorganic filler (C) blended is less than 45 parts by weight based on 100 parts by weight of the polyamide resins (A) and (B).
4. (Original) The polyamide resin composition according to claim 1, further comprising (D) 0.05 to 5 parts by weight of a light stabilizer based on 100 parts by weight of the polyamide (A) and (B).

5. (Original) The polyamide resin composition according to claim 1, further comprising (E) 0.05 to 5 parts by weight of a phenolic antioxidant based on 100 parts by weight of the polyamide (A) and (B).

6. (Original) The polyamide resin composition according to claim 1, further comprising (F) 0.05 to 5 parts by weight of a copper compound, a halide or mixture thereof based on 100 parts by weight of the polyamide (A) and (B).

7. (Original) The polyamide resin composition according to claim 1, wherein relative viscosity of (A) the polyamide 6 resin, polyamide 66 resin or mixture thereof is 1.8 to 3.5.

8. (Presently Amended) The polyamide resin composition according to claim 1, wherein the diamine units comprises 20 to 45 mol% of paraxylylene diamine units and 55 to ~~8~~80 mol% of methaxylylenediamine units.

9. (Original) The polyamide resin composition according to claim 1, wherein the aliphatic dicarboxylic acid is an α,ω -straight-chain aliphatic dicarboxylic acid.

10. (Original) The polyamide resin composition according to claim 1, wherein the aliphatic dicarboxylic acid is an aliphatic dicarboxylic acid having 6 to 12 carbon atoms.

11. (Original) The polyamide resin composition according to claim 1, wherein relative viscosity of the aromatic polyamide resin is 1.6 to 3.0.

12. (Original) The polyamide resin composition according to claim 1, wherein the inorganic filler is a fibrous filler having an average fiber diameter of not more than 14 μm or a powdery, granular or flaky filler having an average particle diameter of not more than 50 μm .

13. (Original) The polyamide resin composition according to claim 1, wherein the inorganic filler (C) is selected from the group consisting of glass fiber, talc and mica.

14. (Original) The polyamide resin composition according to claim 4, wherein the light stabilizer (D) is selected from the group consisting of hindered amines and benzotriazoles.

15. (Original) The polyamide resin composition according to claim 6, wherein the mixture of 0.01 to 2 parts by weight of a copper compound (F') and 0.05 to 3 parts by weight of an alkali metal halide (F'') based on 100 parts by weight of the polyamide resins (A) and (B) is used.

16. (Original) The polyamide resin composition according to claim 1, wherein the whole of the component (A) is a polyamide 6 resin

17. (Previously Presented) A polyamide resin composition consisting essentially of:

100 parts by weight of a polyamide resin mixture comprising

(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof and

(B) 10 to 80% by weight of an aromatic polyamide resin; and

(C) 0 to 300 parts by weight of an inorganic filler,

said aromatic resin mainly comprising polyamide obtained from polycondensation reaction of a diamine mixture comprising 10 to 50 mol% of paraxylylenediamine and 50 to 90 mol% of methaxylylenediamine, and an aliphatic dicarboxylic acid.

18. (Original) A molded article for outdoor use, obtained by molding a polyamide resin composition as defined in claim 1.

19. (Original) The molded article according to claim 18, obtained by a polyamide resin composition in which melt viscosity of (A) the polyamide 6 resin, polyamide 66 resin or mixture thereof is lower than that of the aromatic polyamide resin (B).

20. (Original) The molded article according to claim 18, obtained by molding a polyamide resin composition in which melt viscosity of (A) the polyamide 6 resin, polyamide 66 resin or mixture thereof is higher than that of the aromatic polyamide resin (B).

21. (Previously Presented) The polyamide resin composition according to claim 1, wherein a molded article obtained from molding the polyamide resin composition at between 70°C and 90°C by a #3000 mirror-polished mold has a glossiness of the surface of not less than 80%.

22. (Previously Presented) A polyamide resin composition consisting essentially of:

100 parts by weight of a polyamide resin mixture comprising

(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof and

(B) 10 to 80% by weight of an aromatic polyamide resin, said aromatic polyamide resin having diamine units comprising 10 to 50 mol% of paraxylylenediamine units and 50 to 90 mol% of methaxylylenediamine units, and aliphatic dicarboxylic acid units;

(C) 0 to 300 parts by weight of an inorganic filler; and

one or more additives selected from the group consisting of antistatic agent, coloring material, release agent, lubricant, plasticizer, nucleating agent, and stabilizers.

23. (Previously Presented) A molded article produced by injection molding, which comprises a polyamide resin composition consisting essentially of:

100 parts by weight of a polyamide resin mixture comprising

(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof and

(B) 10 to 80% by weight of an aromatic polyamide resin; and

(C) 0 to 300 parts by weight of an inorganic filler,

said aromatic polyamide resin having diamine units comprising 10 to 50 mol% of paraxylylenediamine units and 50 to 90 mol% of methaxylylenediamine units, and aliphatic dicarboxylic acid units.

24. (Previously Presented) A molded article according to claim 23, wherein the injection molding is conducted by use of a mirror-polished mold.

25. (Previously Presented) A molded article according to claim 23, wherein the flexural modulus of elasticity is not less than 10 GPa at room temperature (23°C) and not less than 7 GPa at 80°C.

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Listing of claims:

1. (Previously Amended) A polyamide resin composition consisting essentially of:
100 parts by weight of a polyamide resin mixture comprising
(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof
and
(B) 10 to 80% by weight of an aromatic polyamide resin;
and
(C) 0 to 300 parts by weight of an inorganic filler,
said aromatic polyamide resin having diamine units comprising 10 to 50 mol% of paraxylylenediamine units and 50 to 90 mol% of methaxylylenediamine units, and aliphatic dicarboxylic acid units.
2. (Original) The polyamide resin composition according to claim 1, wherein the amount of the inorganic filler (C) blended is 45 to 150 parts by weight based on 100 parts by weight of the polyamide resins (A) and (B).
3. (Original) The polyamide resin composition according to claim 1, wherein the amount of the inorganic filler (C) blended is less than 45 parts by weight based on 100 parts by weight of the polyamide resins (A) and (B).
4. (Withdrawn) The polyamide resin composition according to claim 1, further comprising (D) 0.05 to 5 parts by weight of a light stabilizer based on 100 parts by weight of the polyamide (A) and (B).

5. (Withdrawn) The polyamide resin composition according to claim 1, further comprising (E) 0.05 to 5 parts by weight of a phenolic antioxidant based on 100 parts by weight of the polyamide (A) and (B).

6. (Withdrawn) The polyamide resin composition according to claim 1, further comprising (F) 0.05 to 5 parts by weight of a copper compound, a halide or mixture thereof based on 100 parts by weight of the polyamide (A) and (B).

7. (Original) The polyamide resin composition according to claim 1, wherein relative viscosity of (A) the polyamide 6 resin, polyamide 66 resin or mixture thereof is 1.8 to 3.5.

8. (Original) The polyamide resin composition according to claim 1, wherein the diamine units comprises 20 to 45 mol% of paraxylylene diamine units and 55 to 8 mol% of methaxylylenediamine units.

9. (Original) The polyamide resin composition according to claim 1, wherein the aliphatic dicarboxylic acid is an α,ω -straight-chain aliphatic dicarboxylic acid.

10. (Original) The polyamide resin composition according to claim 1, wherein the aliphatic dicarboxylic acid is an aliphatic dicarboxylic acid having 6 to 12 carbon atoms.

11. (Original) The polyamide resin composition according to claim 1, wherein relative viscosity of the aromatic polyamide resin is 1.6 to 3.0.

12. (Original) The polyamide resin composition according to claim 1, wherein the inorganic filler is a fibrous filler having an average fiber diameter of not more than 14 μm or a powdery, granular or flaky filler having an average particle diameter of not more than 50 μm .

13. (Original) The polyamide resin composition according to claim 1, wherein the inorganic filler (C) is selected from the group consisting of glass fiber, talc and mica.

14. (Withdrawn) The polyamide resin composition according to claim 4, wherein the light stabilizer (D) is selected from the group consisting of hindered amines and benzotriazoles.

15. (Withdrawn) The polyamide resin composition according to claim 6, wherein the mixture of 0.01 to 2 parts by weight of a copper compound (F') and 0.05 to 3 parts by weight of an alkali metal halide (F'') based on 100 parts by weight of the polyamide resins (A) and (B) is used.

16. (Original) The polyamide resin composition according to claim 1, wherein the whole of the component (A) is a polyamide 6 resin

17. (Presently Amended) A polyamide resin composition ~~comprising~~consisting essentially of:

100 parts by weight of a polyamide resin mixture comprising
(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof
and

(B) 10 to 80% by weight of an aromatic polyamide resin; and

(C) 0 to 300 parts by weight of an inorganic filler,

said aromatic resin mainly comprising polyamide obtained from polycondensation reaction of a diamine mixture comprising 10 to 50 mol% of paraxylylenediamine and 50 to 90 mol% of methaxylylenediamine, and an aliphatic dicarboxylic acid.

18. (Original) A molded article for outdoor use, obtained by molding a polyamide resin composition as defined in claim 1.

19. (Original) The molded article according to claim 18, obtained by a polyamide resin composition in which melt viscosity of (A) the polyamide 6 resin, polyamide 66 resin or mixture thereof is lower than that of the aromatic polyamide resin (B).

20. (Original) The molded article according to claim 18, obtained by molding a polyamide resin composition in which melt viscosity of (A) the polyamide 6 resin, polyamide 66 resin or mixture thereof is higher than that of the aromatic polyamide resin (B).

21. (Previously Presented) The polyamide resin composition according to claim 1, wherein a molded article obtained from molding the polyamide resin composition at between 70°C and 90°C by a #3000 mirror-polished mold has a glossiness of the surface of not less than 80%.

22. (Presently Amended) A polyamide resin composition consisting essentially of:
100 parts by weight of a polyamide resin mixture comprising
(A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof
and
(B) 10 to 80% by weight of an aromatic polyamide resin, said aromatic polyamide resin
having diamine units comprising 10 to 50 mol% of paraxylylenediamine units and 50 to 90
mol% of methaxylylenediamine units, and aliphatic dicarboxylic acid units;
(C) 0 to 300 parts by weight of an inorganic filler; and according to claim 1, further
consisting essentially of

one or more additives selected from the group consisting of antistatic agent, coloring material, release agent, lubricant, plasticizer, nucleating agent, and stabilizers.

23. (Previously Presented) A molded article produced by injection molding, which comprises a polyamide resin composition consisting essentially of:
100 parts by weight of a polyamide resin mixture comprising

- (A) 20 to 90% by weight of a polyamide 6 resin, a polyamide 66 resin or mixture thereof and
 - (B) 10 to 80% by weight of an aromatic polyamide resin; and
 - (C) 0 to 300 parts by weight of an inorganic filler,
- said aromatic polyamide resin having diamine units comprising 10 to 50 mol% of paraxylylenediamine units and 50 to 90 mol% of methaxylylenediamine units, and aliphatic dicarboxylic acid units.

24. (Previously Presented) A molded article according to claim 23, wherein the injection molding is conducted by use of a mirror-polished mold.

25. (Previously Presented) A molded article according to claim 23, wherein the flexural modulus of elasticity is not less than 10 GPa at room temperature (23°C) and not less than 7 GPa at 80°C.